



Intel – A Technology Partner for HPC R&D in Europe

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Intel Labs Europe NETWORK

ENGLAND

- Intel Mobile IP Lab Swindon
- Intel Wearable IP Lab Swindon
- Intel High Performance Computing Lab Swindon
- Intel (IOT Ignition) Open Lab Swindon
- Intel fasterLAB Winnersh
- Intel Open Source Technology Center London
- ICRI for Sustainable Connected Cities London
- Intel Digital Communications Lab Borehamwood
- Intel Customer Deployment Engineering Lab Lincoln
- Intel Graphics and Media Lab Egham and Bristol
- Intel Mobile (GPS/GNSS) Lab Daventry
- Intel Security (McAfee) Lab Aylesbury and Brighton
- Intel and BT Co-Lab Ipswich

SWEDEN

- Intel Advanced Rendering Technology Lund
- Intel (IOT Ignition) Lab Stockholm
- Intel Simics Center and IOT Ignition Lab Stockholm

FINLAND

- Intel Open Technology Center Helsinki
- ICRI for Secure Computing Helsinki
- Intel Research and Development Center Tampere

RUSSIA

- Intel Simics Technology Center Moscow
- Intel Labs St. Petersburg
- Intel Software Development Lab Nizhny & Novosibirsk

NORTHERN IRELAND

- Intel Mobile Cloud Computing Lab Belfast
- Intel and SAP Co-Lab Belfast

IRELAND

- Innovation Open Lab (Cloud and Cities Research) Leixlip
- Intel Educational Research Lab Leixlip
- Innovation Value Institute Maynooth
- Intel Embedded Lab Shannon

FRANCE

- Exascale Computing Research Center Paris
- Intel System Modeling and Simulation Center Nantes
- Intel MCG Smartphone & Tablet Labs Toulouse and Nice
- Intel Open Source Technology Center Montpellier
- Intel Mobile Communications Sophia Antipolis
- Intel Wireless Certification Lab Sophia Antipolis

SWITZERLAND

- CERN openlab Geneva

GERMANY

- ExaCluster Laboratory Jülich
- Intel Mobile Communications Dresden, Duisburg, Munich, Nuremberg, Regensburg, Ulm
- ICRI for Secure Computing Darmstadt
- Intel Visual Computing Institute Saarbrücken
- Automotive Innovation & Product Development Center Karlsruhe
- Intel Debugger Tools Lab Ulm
- Intel (IOT Ignition) Open Lab Munich

DENMARK

- Intel Mobile Communications Aalborg

NETHERLANDS

- Intel VIED Center Eindhoven

BELGIUM

- ExaScience Lab Leuven
- Intel Communications Infrastructure Solutions Lab Kontich

AUSTRIA

- Intel Mobile Communications Linz and Villach

POLAND

- Intel Technology Center Gdansk

SERBIA

- Intel VIED Center Belgrade

ROMANIA

- Intel Software Development Center Bucharest
- Intel Educational Software Development Lab Cluj-Napoca

SPAIN

- Intel and BSC Exascale Laboratory Barcelona
- Intel New Devices Lab Seville

TURKEY

- Intel (IOT Ignition) Open Lab Istanbul

ISRAEL

- Intel Israel Open Innovation Center Petach Tikva
- ICRI for Computational Intelligence Haifa

Harnessing the collective value of Intel's R&D investments in Europe

Intel HPC R&D activities in Europe

Software & Solutions Group

- Optimize existing codes on existing Intel HW & SW
- Support OEMs in benchmarks

Intel Parallel Competence Centers (IPCC)

- Optimize existing community codes for Xeon Phi
- Contracts to universities / research labs with 1-2 years perspective

Intel European Exascale Labs

- Focus on “future” applications
- Partner with leading HPC apps developers
- Feedback to Intel architects
- 5-7 years perspective, part of „pathfinding“ process
(*Research* \square *Pathfinding* \square *Development*)
- Engage in H2020 (ETP4HPC, FET-HPC, CoE, ...)





ExaCluster Lab,
Jülich



Leuven



Research Lab, Paris



Intel and BSC
Exascale
Lab, Barcelona



New: Intel-CERN
Lab on Throughput
Computing

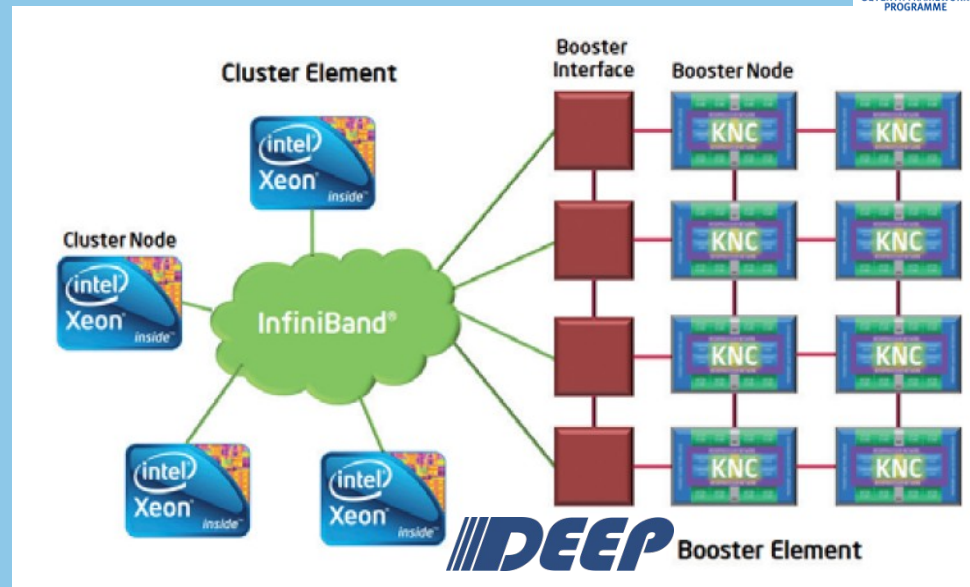


Germany: Juelich ExaCluster Laboratory



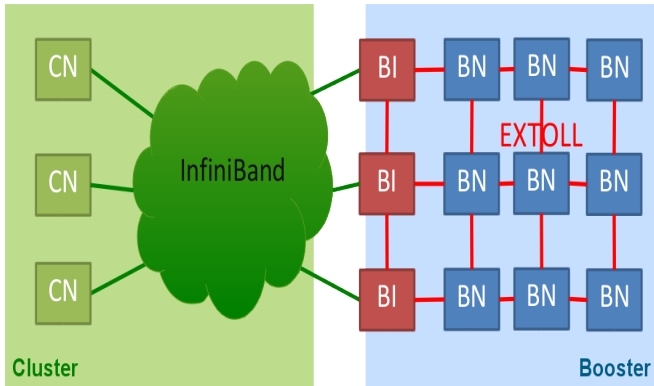
SW Scalability and Resilience
Exascale Cluster Architecture
Exascale Simulation and Tools

The DEEP Architecture

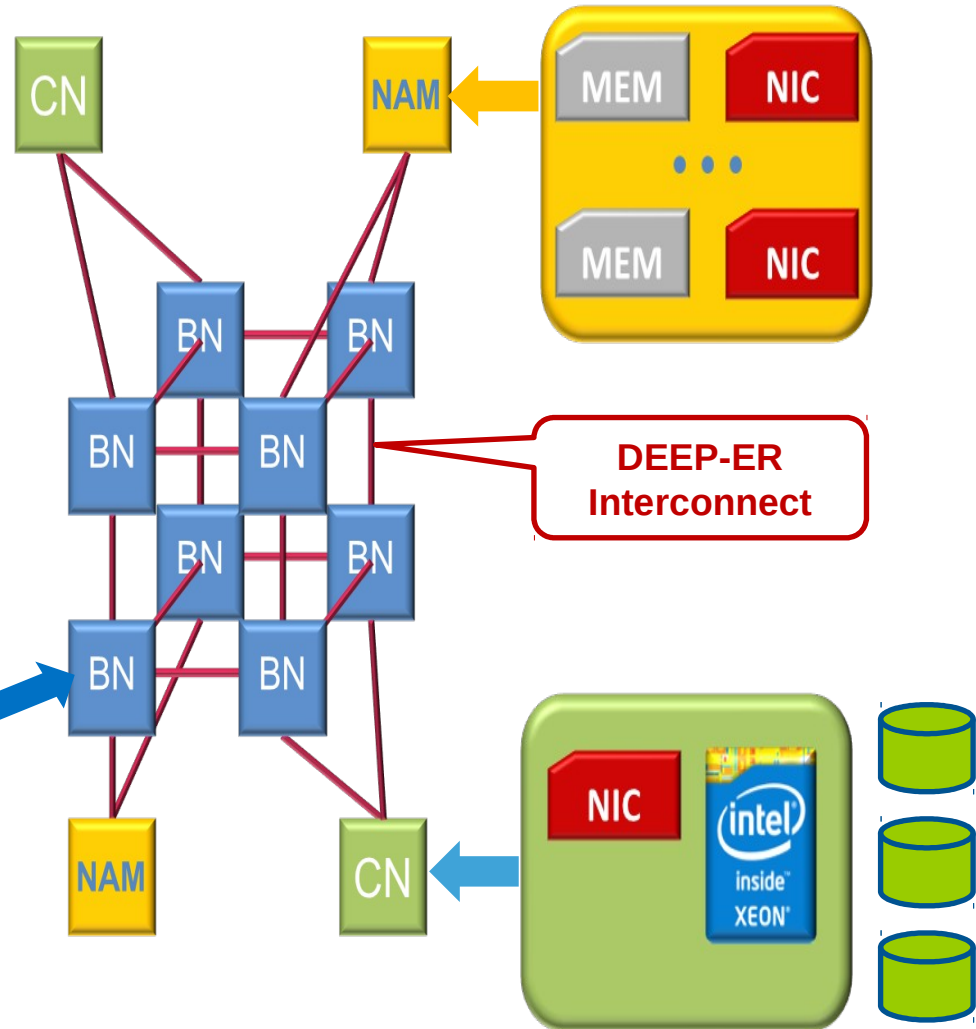


Architecture Evolution

DEEP



DEEP-ER



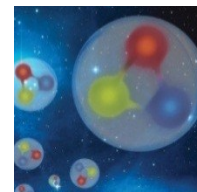
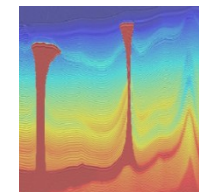
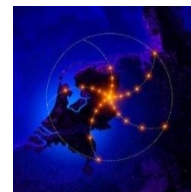
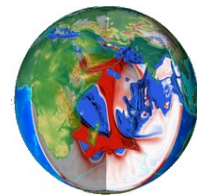
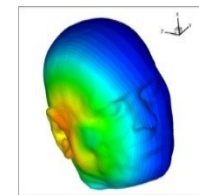
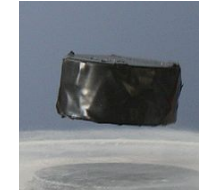
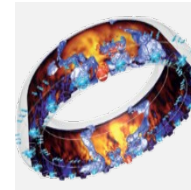
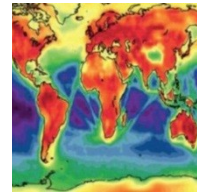
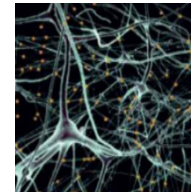
Legend:

- CN: Cluster Node
- BN: Booster Node
- BI: Booster Interface
- KNL: Intel® Xeon Phi™
- NAM: Network Attached Memory
- NVM: Non Volatile Memory

Application-Driven Approach

DEEP & DEEP-ER applications:

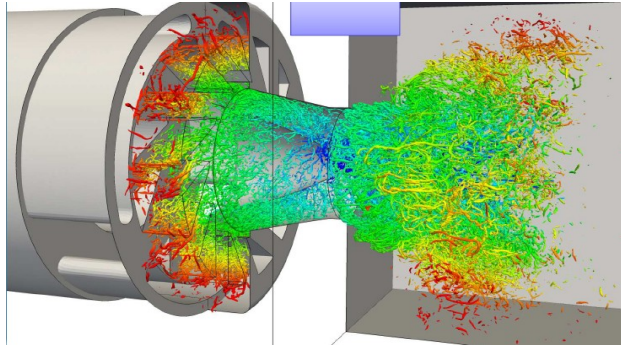
- Brain simulation (EPFL)
- Space weather simulation (KULeuven)
- Climate simulation (CYI)
- Computational fluid engineering (CERFACS)
- High temperature superconductivity (CINECA)
- Seismic imaging (CGGVS)
- Human exposure to electromagnetic fields (INRIA)
- Geoscience (BADW-LRZ)
- Radio astronomy (Astron)
- Oil exploration (BSC)
- Lattice QCD (UREG)



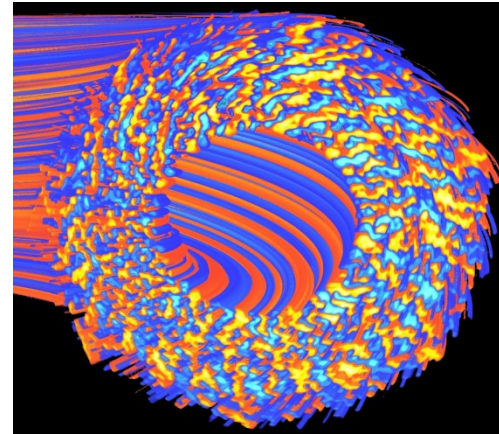
Objectives:

- Co-design & evaluation of DEEP architecture & programmability
- Analysis of the I/O and resiliency requirements of HPC codes

Paris Exascale Lab – Addressing SW Challenges



YALES2



Gysela5

Scaling

- How do codes scale from peta- to exa-scale?
- With MPI + X?

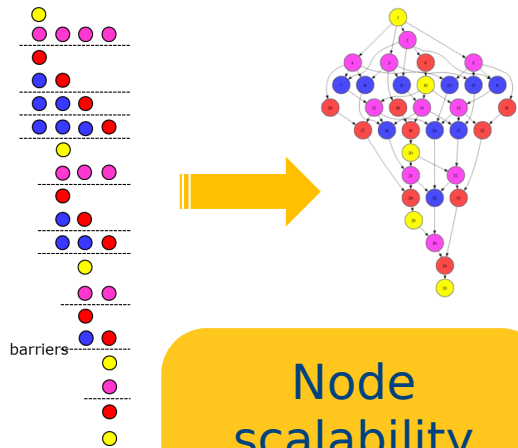
New memory architecture

- cache – DRAM – disk □ cache – high BW local memory – NVM

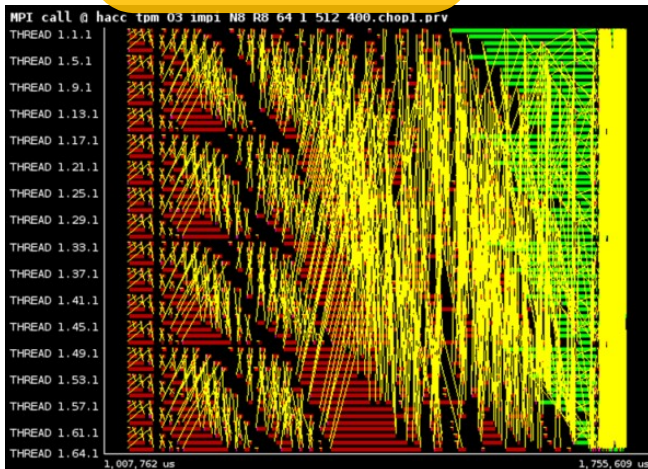
Energy

- How will applications run in a power-bound regime?
- Does it make sense to overlap of calculation and comms?

Barcelona (BSC) Exascale Lab

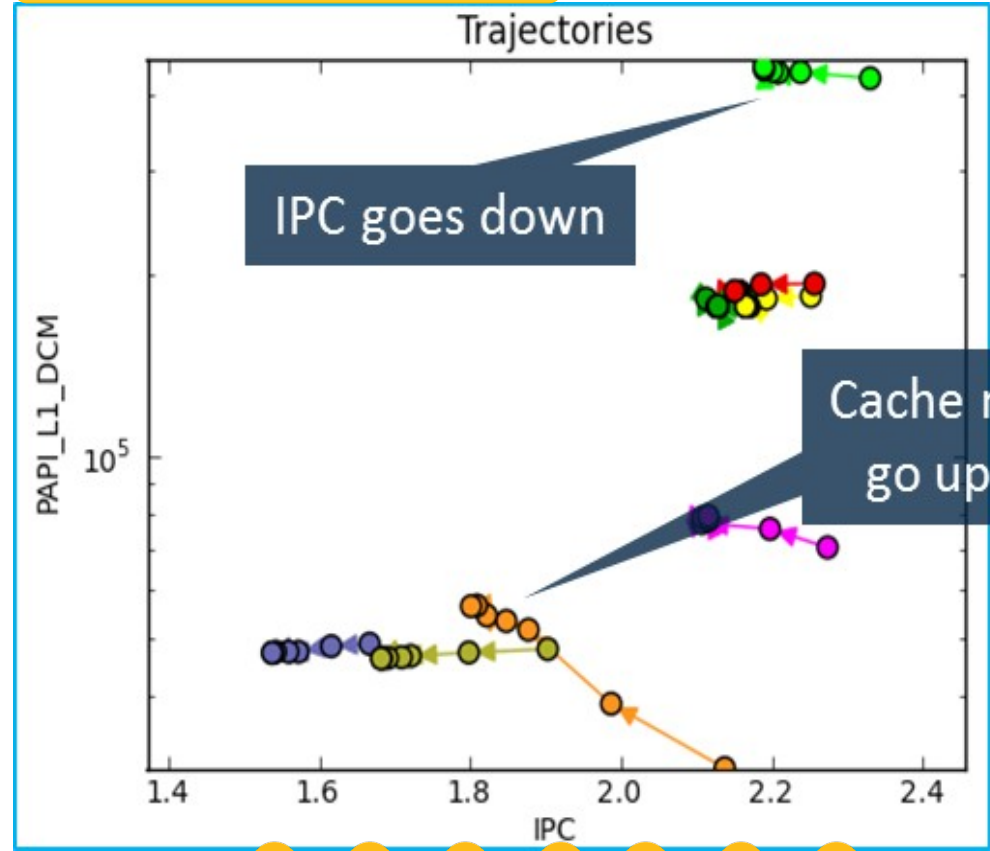


Node scalability improvements



Workload analysis

Code phase analysis



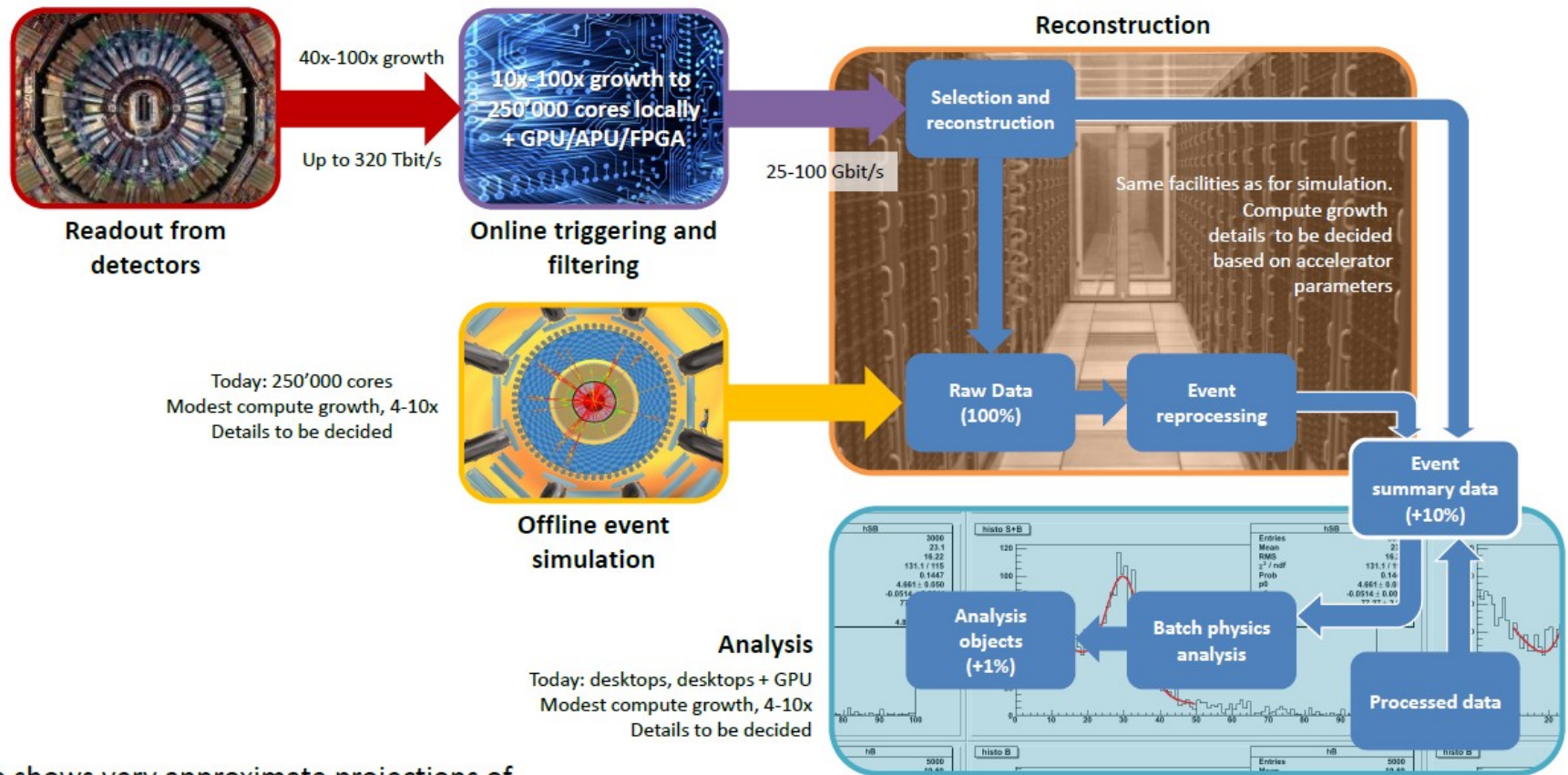
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- 16
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- 8
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- 4
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- 2

IPC goes down

Cache misses go up a lot

LHC Data Flow

Data flow from the LHC detectors: 2018-2022



This slide shows very approximate projections of the LHC data flow around 2018 (after Long Shutdown 2)

CoE: Intel's potential contribution and role

Can we establish a „co-design“ process?

- Can the community agree on a codes / mini-apps / kernels / libraries ...
- Analyze requirements and present to architects
- Intel to provide fast simulator to the CoE community?

How to collaborate?

- Big issue: confidentiality vs IP rules of H2020/CoE?
 - Intel needs to understand IP rules early
- Keep links to different vendors separate
- Vendors part of the consortium (i.e. signing the CA)?